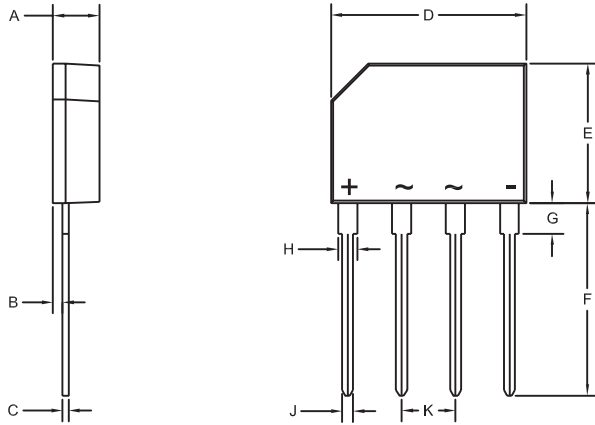


# Package Details - Case B-M

## Mechanical Drawing



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.132	0.144	3.35	3.65
B	0.031	0.043	0.80	1.10
C	0.012	0.025	0.30	0.64
D	0.561	0.581	14.25	14.75
E	0.402	0.417	10.20	10.60
F	0.561	0.580	14.25	14.73
G	0.083	0.098	2.10	2.50
H	0.046	0.056	1.17	1.42
J	0.030	0.034	0.76	0.86
K	0.140	0.160	3.56	4.06

Case B-M (REV: R1)

R1

### Lead Code:

As indicated on mechanical drawing.

### Packing options:

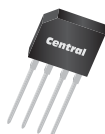
#### Bulk - Packing Code: C

C = Anti-static coated sleeves.

**Bulk Packing Quantity:** 35 per sleeve

# Material Composition Specification

## Case B-M



Device average mass ..... 177 mg  
 Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.18%	1.2	Si	7440-21-3	0.68%	1.2	6,780
leadframe	copper	9.33%	61.6	Cu	7440-50-8	34.8%	61.6	348,023
die attach	high temperature solder	0.42%	2.8	Pb	7439-92-1	1.47%	2.6	14,689
				Sn	7440-31-5	0.11%	0.2	1,130
encapsulation	EMC	16.36%	108	Silica	7631-86-9	33.33%	59.0	333,333
				brominated epoxy resin	Proprietary	25.14%	44.5	251,412
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	2.54%	4.5	25,424
plating*	tin/lead process	0.52%	3.4	Sn	7440-31-5	1.58%	2.8	15,819
				Pb	7439-92-1	0.34%	0.6	3,390
	100% tin process	0.52%	3.4	Sn	7440-31-5	1.92%	3.4	19,209

\*For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

### Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)